



ELECTRONIC SOLDERS

BLF 227 LEAD-FREE ALLOY Technical Data Sheet

DESCRIPTION

Bow Electronic Solders has developed BLF 227, a low-cost Lead Free bar solder. BLF 227 is a near eutectic Tin/Copper/Nickel alloy. This alloy is proven to perform well in surface mount, wave soldering, and hand soldering applications. BLF 227 alloy may be used with existing equipment, processes, coatings, and flux chemistries. BLF 227 alloy is available in bar, cored wire, solid wire, foil, and preforms. Bow BLF 227 compares favorably to other low-cost, lead-free alloys of tin and copper in wetting and flow characteristics. BLF 227 is manufactured to J-STD-006 or better.

FEATURES

- Low cost, lead-free alloy
- Smooth solder joints with no visible shrinkage effects
- Excellent through-hole penetration and topside fillet
- Low dissolution of copper from boards and components into solder pot
- Near Eutectic alloy melting point of 227°C
- ROHS Complaint
- Unique Shape

FLUX COMPATIBILITY

BLF 227 alloy is compatible with many major electronic grade fluxes on the market today, and is available in wire form in no-clean and rosin chemistries.

TEMPERATURE REQUIREMENTS

APPLICATION	RECOMMENDED TEMPERATURE
REFLOW SOLDERING	PEAK TEMPERATURE 210°-235°C (410°-455° F)
WAVE SOLDERING	POT TEMPERATURE OF 265°-280°C (520°-536°F)
HAND SOLDERING	TIP TEMPERATURE OF 370°-425°C (700°-800°)

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